CLAIMS

[Claim 1] A polishing liquid for polishing a member to be polished containing a resin, the polishing liquid comprising abrasive grains containing cerium oxide and an ether compound having a hydroxy group, wherein the ether compound includes a compound having one ether group.

[Claim 2] The polishing liquid according to claim 1, wherein the ether compound includes an alkoxy alcohol.

[Claim 3] The polishing liquid according to claim 2, wherein the ether compound includes an alkoxy alcohol having a molecular weight of less than 200.

[Claim 4] The polishing liquid according to claim 2, wherein the alkoxy alcohol includes a compound having an alkoxy group having 1 to 5 carbon atoms.

[Claim 5] The polishing liquid according to claim 2, wherein the alkoxy alcohol includes 1-propoxy-2-propanol.

[Claim 6] The polishing liquid according to claim 2, wherein the alkoxy alcohol includes 3-methoxy-3-methyl-1-butanol.

[Claim 7] The polishing liquid according to claim 2, wherein a content of the alkoxy alcohol is 0.2 to 0.8% by mass on the basis of the total mass of the polishing liquid.

[Claim 8] The polishing liquid according to claim 2, wherein the ether compound further includes a polyether.

[Claim 9] The polishing liquid according to claim 8, wherein the polyether includes polyglycerol.

[Claim 10] The polishing liquid according to claim 8, wherein a

content of the polyether is 0.5 to 3% by mass on the basis of the total mass of the polishing liquid.

[Claim 11] The polishing liquid according to claim 1, wherein a content of the abrasive grains is 0.5 to 2% by mass on the basis of the total mass of the polishing liquid.

[Claim 12] The polishing liquid according to claim 1, further comprising an organic acid component.

[Claim 13] The polishing liquid according to claim 1, further comprising at least one selected from the group consisting of an ammonium cation and ammonia.

[Claim 14] The polishing liquid according to claim 1, wherein a pH is 9.00 to 11.00.

[Claim 15] A polishing method, comprising: polishing a member to be polished containing a resin by using the polishing liquid according to any one of claims 1 to 14.

[Claim 16] The polishing method according to claim 15, wherein the resin includes an epoxy resin.

[Claim 17] The polishing method according to claim 15, wherein the member to be polished further contains particles containing silicon oxide.

[Claim 18] A method for manufacturing a component, comprising: obtaining a component by using a polished member polished by the polishing method according to claim 15.

[Claim 19] A method for manufacturing a semiconductor component, comprising: obtaining a semiconductor component by using a polished member polished by the polishing method according to claim 15.